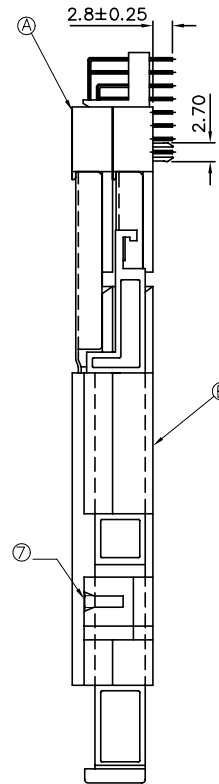
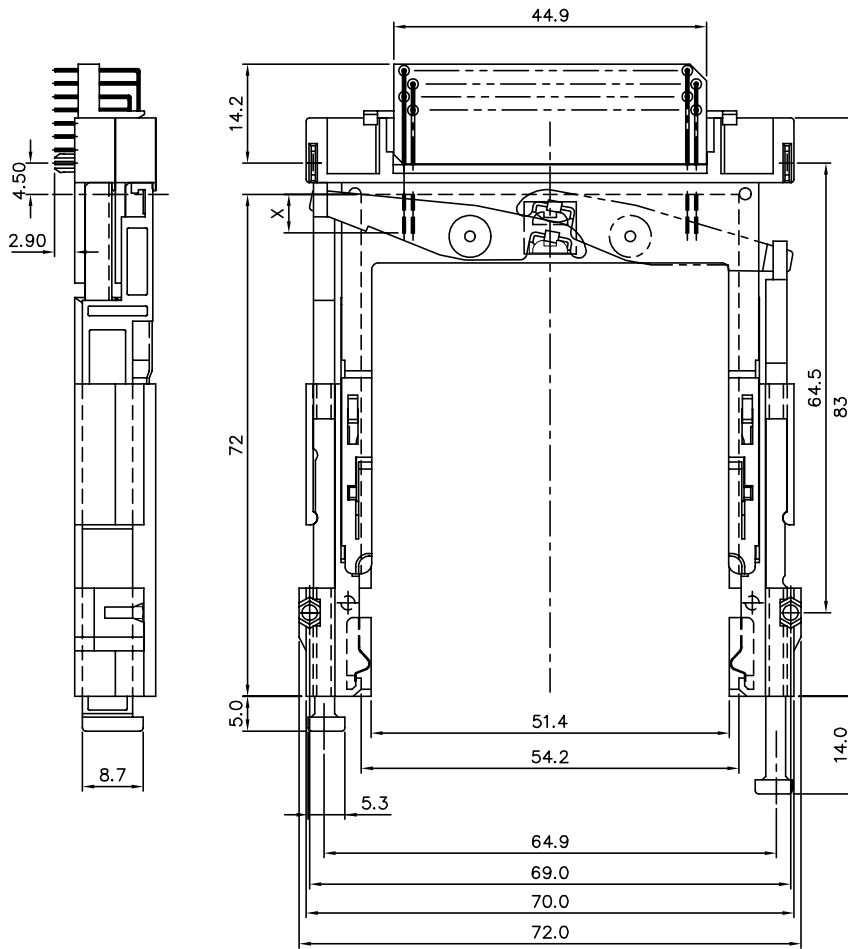


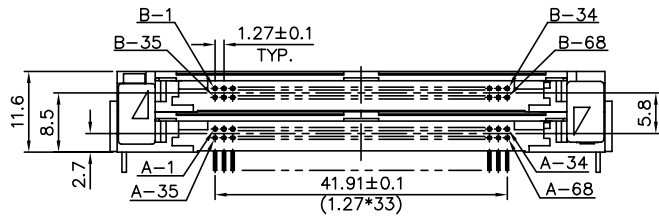
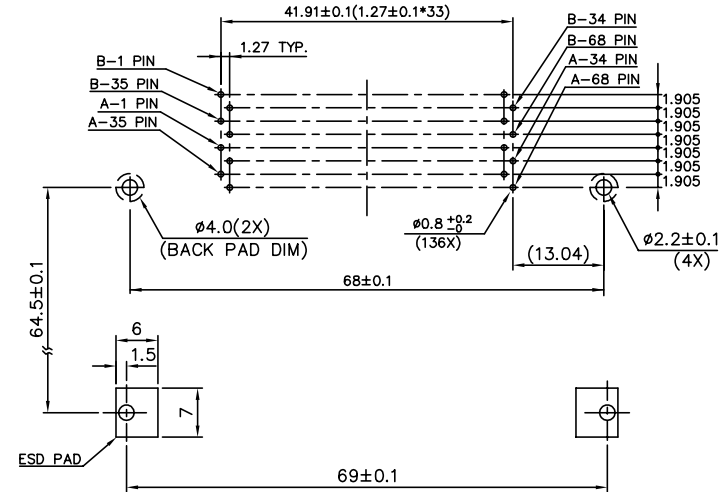
PRODUCT NO.
94721-001CA/001CALF



NOTES:

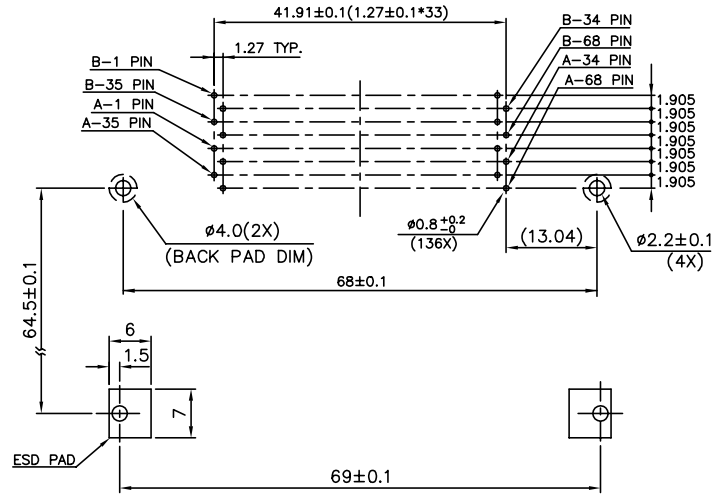
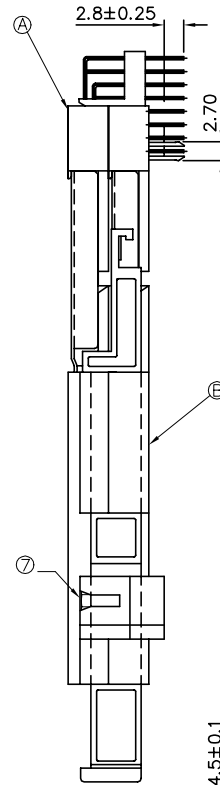
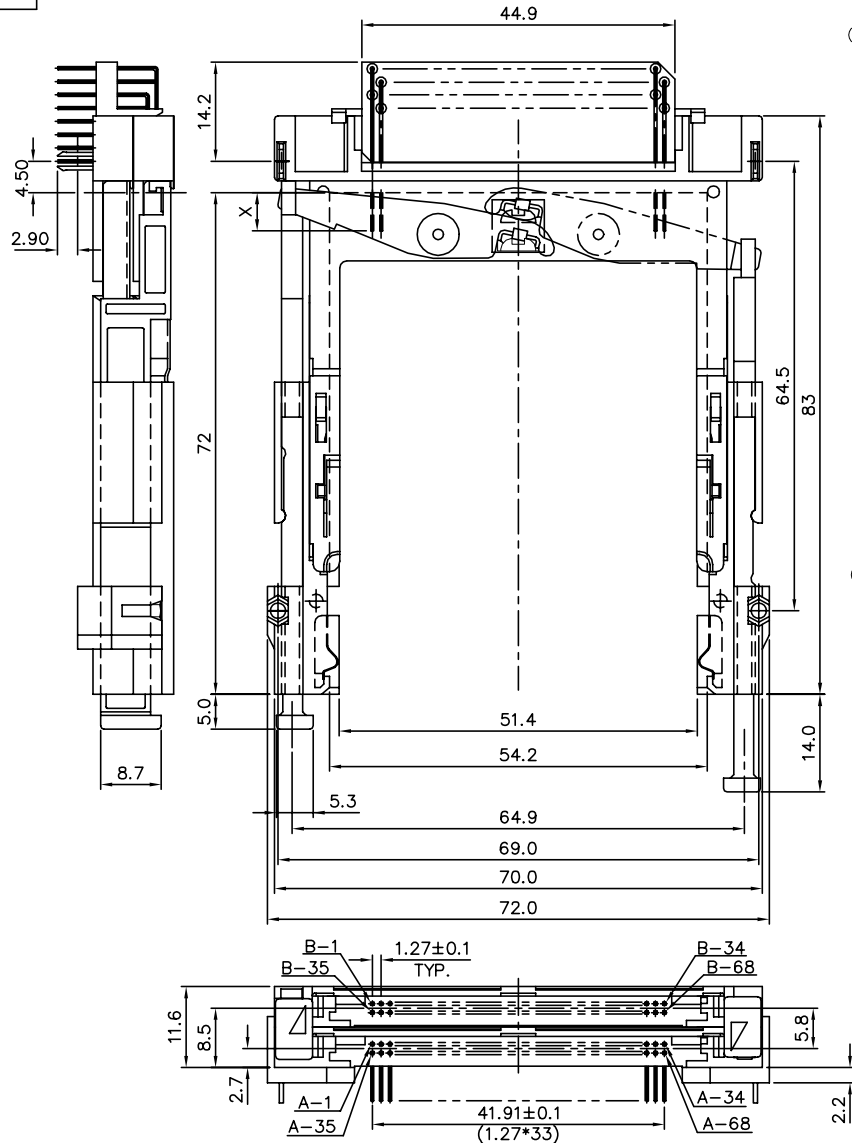
1. EJECT FORCE 3.5 Kg MAX.
2. ASS'Y PROCESS
 - 2.1 TO MOUNT PART (A) ON PWB WITH HOLD DOWN(S1,S2)AND SOLDER THEN FIX PART (B) WITH TWO SCREWS.
3. EJECT TRAVEL: 9.0mm
4. MATERIAL
 - 4.1 PART (A) (HEADER ASS'Y)
PLASTIC :HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PIN :COPPER ALLOY
 - 4.2 PART (B) (EJECT MECHANISM ASS'Y)
PLASTIC :HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PLATE :STAINLESS
EMI CONTACT:PHOSPHOR BRONZE
5. FINISH (PIN)
 - UNDER PLATING : 0.5µm MIN. Ni
 - CONTACT AREA : 0.076 µm MIN. GOLD
 - SOLDER TAIL : 2.5µm MIN. Sn-Pb
 - : 2.5µm MIN. PURE Sn (FOR -*****LF)
6.

DIM "X"	4.25±0.1	3.5±0.1	5.0±0.1
PIN NUMBER	OTHERS	36,67	1,17,34,35,51,68
7. NUT M2*0.4P (2X) RETENTION FORCE : 1Kg MIN.
- 8 IF LEAD FREE P.N.THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
- 9 IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
- 10 LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION
- 11 PRODUCT SPEC: 110-263



mat'l. code		surface ISO1302 ✓		tolerance ISO406 ISO1101		projection		product family PCMCIA		
l t r e c n n o d r		date		tolerances unless otherwise specified		MM		68POS. EJECTOR HEADER ASS'Y FOR TYPE 1/2/3		
K	N05-174	WB	06/16/05	angle	0.X±0.3	MM		dwg no		
L	BLX-N-007963	ZK	11/01/11	0°±2'	0.XX±0.13	scale: 1.5:1		sheet 1 of 12 size		
M	BLX-N-011435	ZK	04/23/12		0.XXX±0.05			94721 A4		
F	T50218	WL	0726/95	dr	C L FENG	04/06/94	FCI		type Product Customer Drawing	
G	T50236	WL	0815/95	eng	JOSEPH HSIA	04/06/94				
H	T60040	WL	01/30/96	chr	JOSEPH HSIA	04/06/94				
J	T60486	WL	12/09/96	app	D K WANG	04/06/94				
sheet index	revision	M	M	M	M	M	M	M	M	M
	sheet	1	2	3	4	5	6	7	8	9

PRODUCT NO.
94721-002CA/002CALF



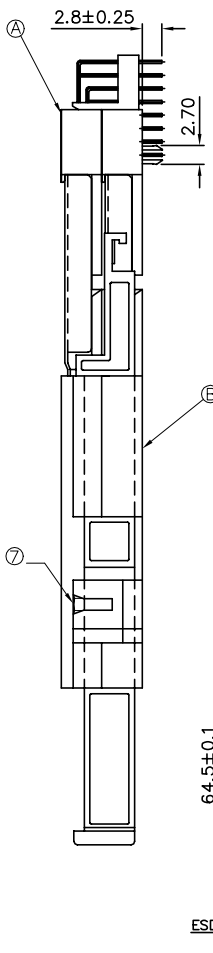
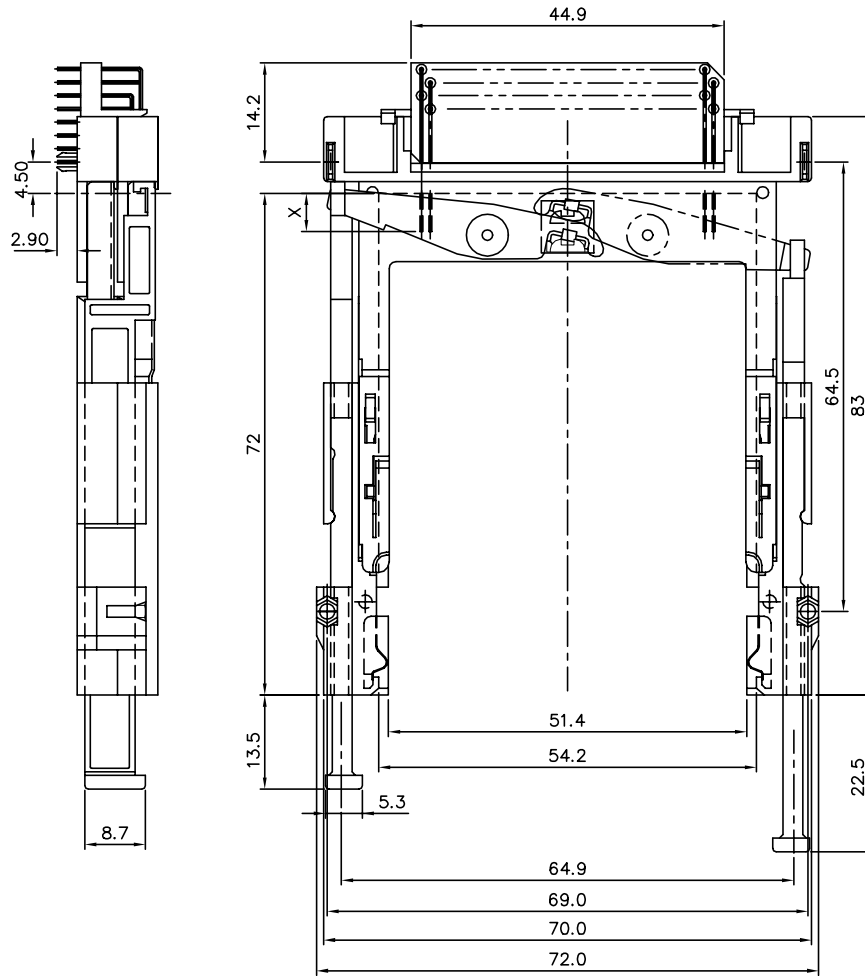
NOTES:

1. EJECT FORCE 3.5 Kg MAX.
2. ASS'Y PROCESS
- 2.1 TO MOUNT PART (A) ON PWB WITH HOLD DOWN(S1,S2)AND SOLDER THEN FIX PART (B) WITH TWO SCREWS.
3. EJECT TRAVEL: 9.0mm
- (A) MATERIAL
- 4.1 PART (A) (HEADER ASS'Y)
PLASTIC :HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PIN :COPPER ALLOY
- 4.2 PART (B) (EJECT MECHANISM ASS'Y)
PLASTIC :HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PLATE :STAINLESS
EMI CONTACT:PHOSPHOR BRONZE
5. FINISH (PIN)
UNDER PLATING :0.5µm MIN. NI
CONTACT AREA :0.076 µm MIN. GOLD
SOLDER TAIL : 2.5µm MIN. Sn-Pb
 : 2.5µm MIN. PURE Sn (FOR -*****LF)
6.

DIM "X"	4.25±0.1	3.5±0.1	5.0±0.1
PIN NUMBER	OTHERS	36,67	1,17,34,35,51,68
- (B) NUT M2*0.4P (2X) RETENTION FORCE : 1Kg MIN.
- 8 IF LEAD FREE P/N.THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
- 9 IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
- 10 LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION
- 11 PRODUCT SPEC: 110-263

mat'l. code	surface ISO1302	tolerance ISO406 ISO1101	projection	product family PCMCIA
l trechn nodr date	tolerances unless otherwise specified		MM	68POS. EJECTOR HEADER ASS'Y FOR TYPE 1/2/3
M	angle	0.X±0.3	scale	1.5:1
	0°±2'	0.XX±0.13		
		0.XXX±0.05		
dr	c L FENG	04/06/94		dwg no
eng	JOSEPH HSIA	04/06/94		sheet 2 of 12
chr	JOSEPH HSIA	04/06/94		size
app	D K WANG	04/06/94		A4
sheet index	revision sheet			type Product Customer Drawing

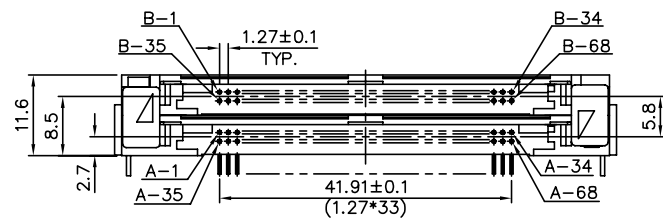
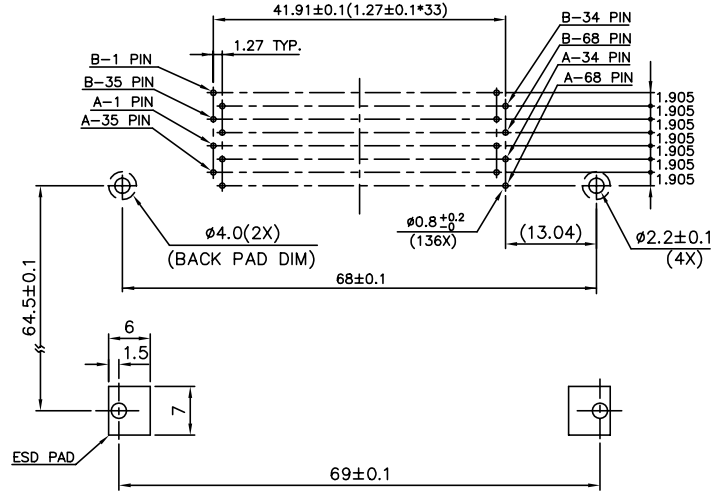
PRODUCT NO.
94721-001DA/001DALF



- NOTES:
- EJECT FORCE 3.5 Kg MAX.
 - ASSY PROCESS
 - TO MOUNT PART A ON PWB WITH HOLD DOWN(S1,S2)AND SOLDER THEN FIX PART B WITH TWO SCREWS.
 - EJECT TRAVEL: 9.0mm
 - MATERIAL
 - PART A (HEADER ASS'Y)
PLASTIC :HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PIN :COPPER ALLOY
 - PART B (EJECT MECHANISM ASS'Y)
PLASTIC :HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PLATE :STAINLESS
EMI CONTACT:PHOSPHOR BRONZE
 - FINISH (PIN)
 - UNDER PLATING :0.5µm MIN. NI
CONTACT AREA :0.076 µm MIN. GOLD
SOLDER TAIL : 2.5µm MIN. Sn-Pb
SOLDER TAIL : 2.5µm MIN. PURE Sn (FOR -****LF)

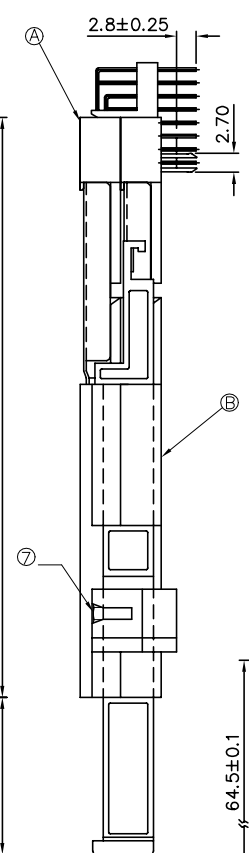
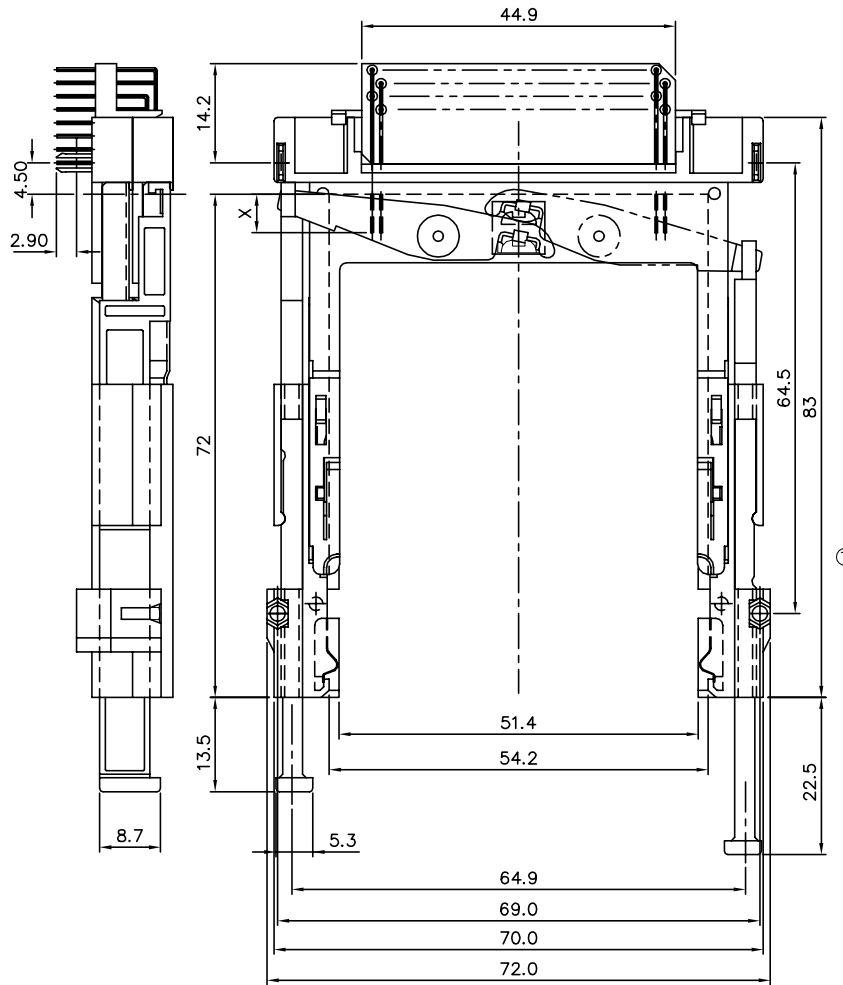
DIM "X"	4.25±0.1	3.5±0.1	5.0±0.1
PIN NUMBER	OTHERS	36,67	1,17,34,35,51,68

- NUT M2*0.4P (2X) RETENTION FORCE : 1Kg MIN.
- IF LEAD FREE P.N.THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
- IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
- LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION
- PRODUCT SPEC: 110-263



mat'l. code	surface ISO1302	tolerance ISO406 ISO1101	projection	product family PCMCIA
l'tecn nodr	date	tolerances unless otherwise specified	MM	68POS. EJECTOR HEADER ASS'Y FOR TYPE 1/2/3
M		angle 0°±2'	scale:1.5:1	dwg no 94721
		dr c L FENG 04/06/94		sheet 3 of 12 size A4
		eng JOSEPH HSIA 04/06/94		type Product Customer Drawing
		chr JOSEPH HSIA 04/06/94		
		app D K WANG 04/06/94		
sheet index	revision sheet			

PRODUCT NO.
94721-002DA/002DALF

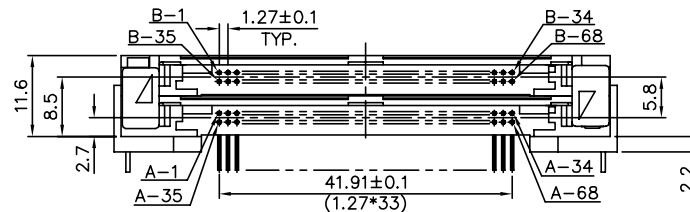
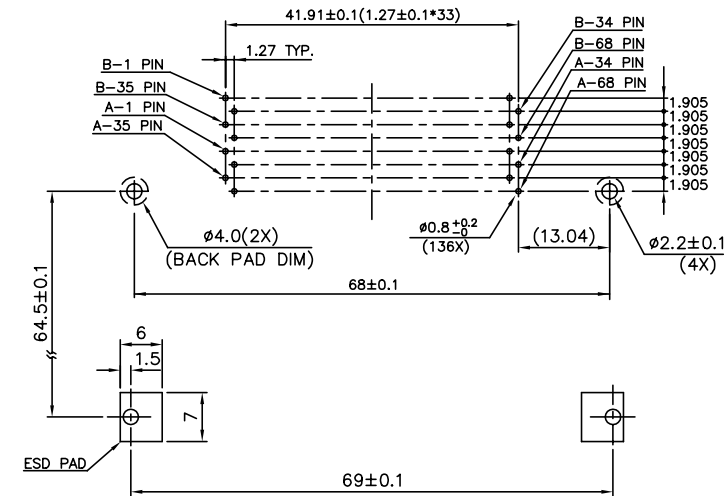


NOTES:

- EJECT FORCE 3.5 Kg MAX.
- ASS'Y PROCESS
 - TO MOUNT PART A ON PWB WITH HOLD DOWN(S1,S2) AND SOLDER THEN FIX PART B WITH TWO SCREWS.
- EJECT TRAVEL: 9.0mm
- MATERIAL
 - PART A (HEADER ASS'Y)
PLASTIC : HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PIN : COPPER ALLOY
 - PART B (EJECT MECHANISM ASS'Y)
PLASTIC : HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PLATE : STAINLESS
EMI CONTACT: PHOSPHOR BRONZE
- FINISH (PIN)
 - UNDER PLATING : 0.5µm MIN. Ni
CONTACT AREA : 0.076 µm MIN. GOLD
SOLDER TAIL : 2.5µm MIN. Sn-Pb
SOLDER TAIL : 2.5µm MIN. PURE Sn (FOR -*****LF)

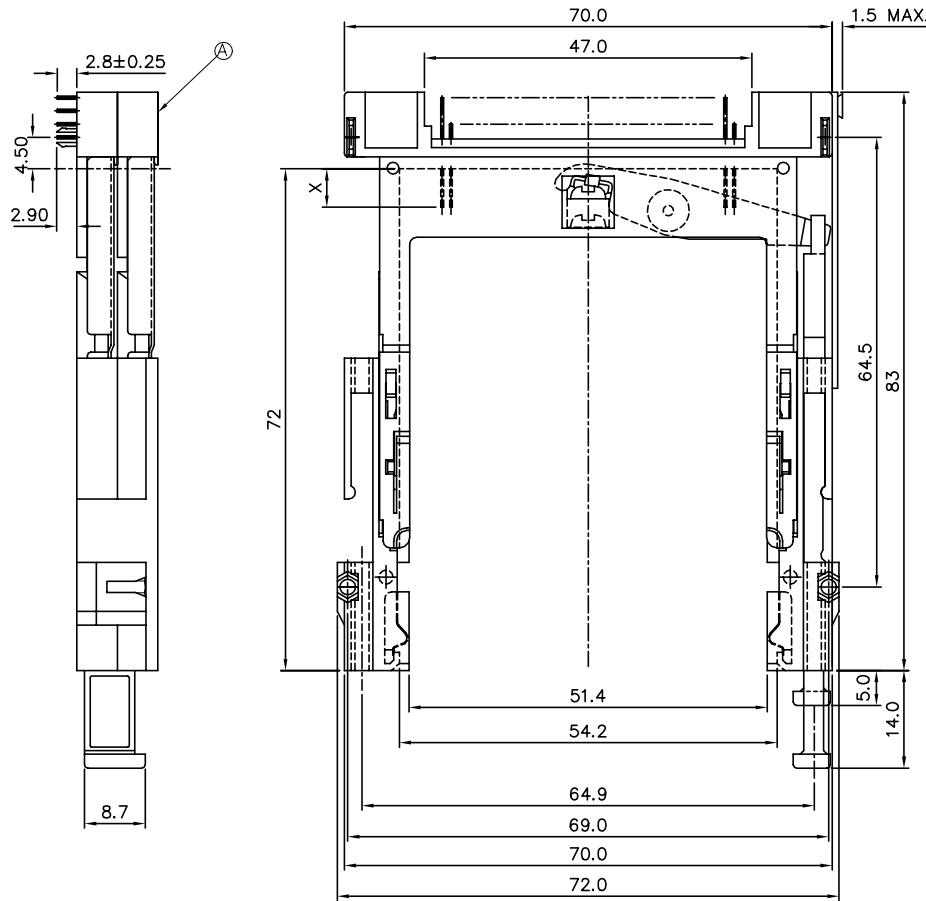
DIM "X"	4.25±0.1	3.5±0.1	5.0±0.1
PIN NUMBER	OTHERS	36,67	1,17,34,35,51,68

- NUT M2*0.4P (2X) RETENTION FORCE : 1Kg MIN.
- IF LEAD FREE P/N.THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
- IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
- LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION
- PRODUCT SPEC: 110-263



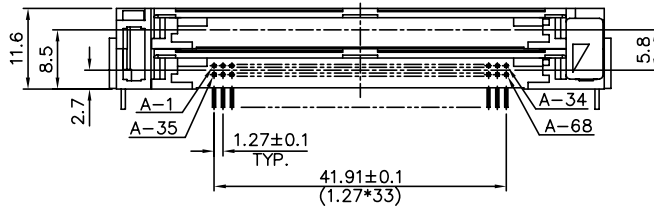
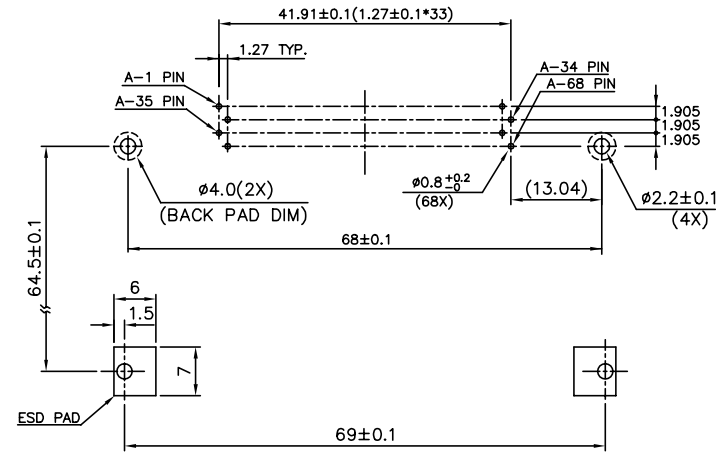
mat'l. code	surface ISD1302	tolerance ISD406 ISD1101	projection	product family PCMCIA
ltr ecn nodr date	tolerances unless otherwise specified	angle 0°±2'	MM	title 68POS. EJECTOR HEADER ASS'Y FOR TYPE 1/2/3
M	0.X±0.3	0.XX±0.13	scale: 1.5:1	dwg no 94721
	0.XXX±0.05			sheet 4 of 12 size A4
	dr C L FENG 04/06/94	engr JOSEPH HSIA 04/06/94	FCI	type Product Customer Drawing
	chr JOSEPH HSIA 04/06/94	app'd D K WANG 04/06/94		
sheet index	revision sheet			

PRODUCT NO.
94721-003CA/003CALF



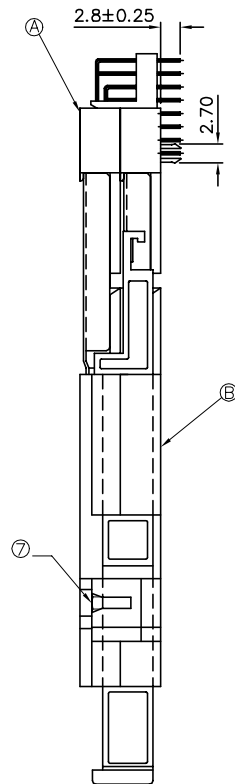
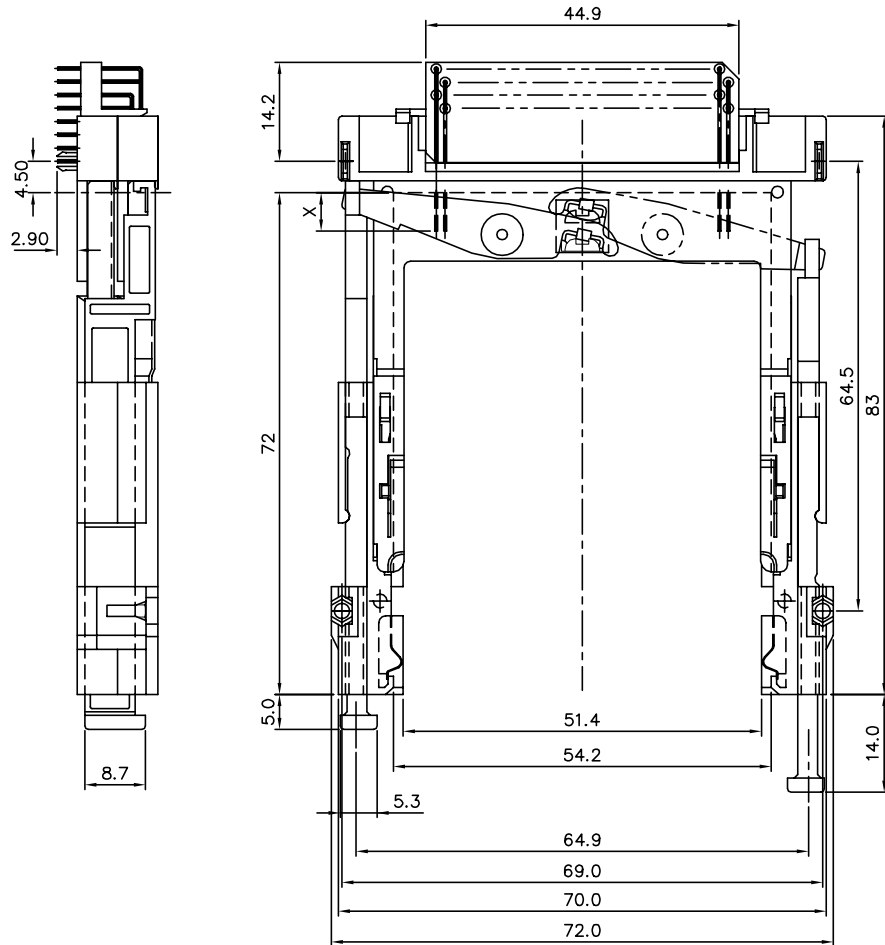
NOTES:

- EJECT FORCE 3.5 Kg MAX.
- ASS'Y PROCESS
- TO MOUNT PART (A) ON PWB WITH HOLD DOWN(S1,S2)AND SOLDER THEN FIX PART (B) WITH TWO SCREWS.
- EJECT TRAVEL: 9.0mm
- (A) MATERIAL
 - PART (A) (HEADER ASS'Y)
PLASTIC : HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PIN : COPPER ALLOY
 - PART (B) (EJECT MECHANISM ASS'Y)
PLASTIC : HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PLATE : STAINLESS
EMI CONTACT: PHOSPHOR BRONZE
- FINISH (PIN)
UNDER PLATING : 0.5µm MIN. NI
CONTACT AREA : 0.076 µm MIN. GOLD
SOLDER TAIL : 2.5µm MIN. Sn-Pb
 : 2.5µm MIN. PURE Sn (FOR -*****LF)
- | DIM "X" | 4.25±0.1 | 3.5±0.1 | 5.0±0.1 |
|------------|----------|---------|------------------|
| PIN NUMBER | OTHERS | 36,67 | 1,17,34,35,51,68 |
- NUT M2*0.4P (2X) RETENTION FORCE : 1Kg MIN.
- IF LEAD FREE P/N.THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM THICK CIRCUIT BOARD.
- IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
- LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION
- PRODUCT SPEC: 110-263



mat'l. code	surface	tolerance	projection	product family
	ISO1302	ISO406 ISO1101		PCMCIA
l trechn nodr date	tolerances unless otherwise specified			
M	angle	0.X±0.3	MM	68POS. EJECTOR HEADER ASS'Y FOR TYPE 1/2/3
	0°±2'	0.XX±0.13	scale: 1.5:1	
		0.XXX±0.05		
dr	c L FENG	04/06/94		dwg no
enr	JOSEPH HSIA	04/06/94		sheet 5 of 12
chr	JOSEPH HSIA	04/06/94		size
app	D K WANG	04/06/94		A4
sheet index	revision sheet			type Product Customer Drawing

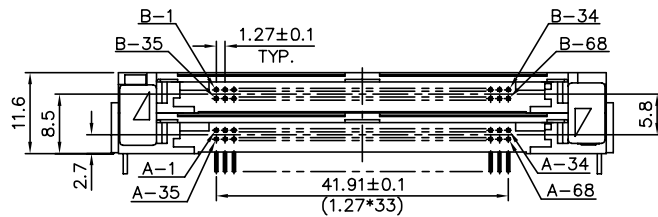
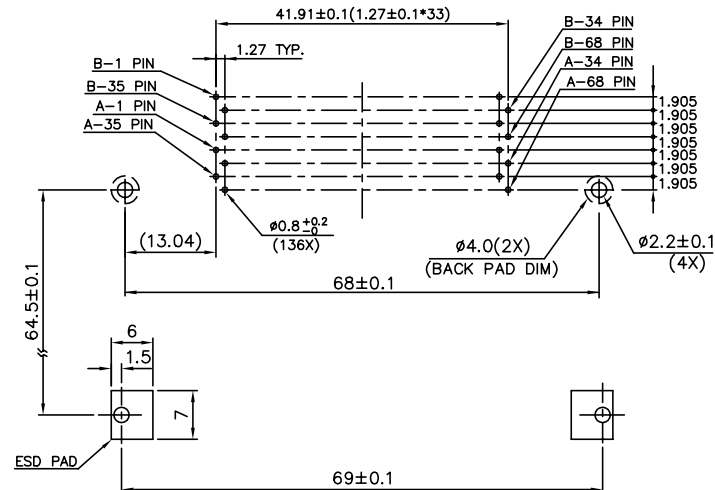
PRODUCT NO.
94721-004CA/004CALF



NOTES:

1. EJECT FORCE 3.5 Kg MAX.
2. ASS'Y PROCESS
- 2.1 TO MOUNT PART A ON PWB WITH HOLD DOWN(S1,S2)AND SOLDER THEN FIX PART B WITH TWO SCREWS.
3. EJECT TRAVEL: 9.0mm
4. MATERIAL
- 4.1 PART A (HEADER ASS'Y)
PLASTIC :HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PIN :PHOSPHOR BRONZE
- 4.2 PART B (EJECT MECHANISM ASS'Y)
PLASTIC :HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PLATE :STAINLESS
EMI CONTACT:PHOSPHOR BRONZE
5. FINISH (PIN)
UNDER PLATING :0.5µm MIN. NI
CONTACT AREA :0.076 µm MIN. GOLD
SOLDER TAIL : 2.5µm MIN. Sn-Pb
: 2.5µm MIN. PURE Sn (FOR -*****LF)
6.

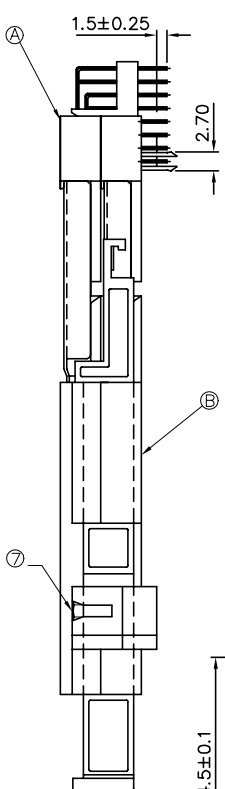
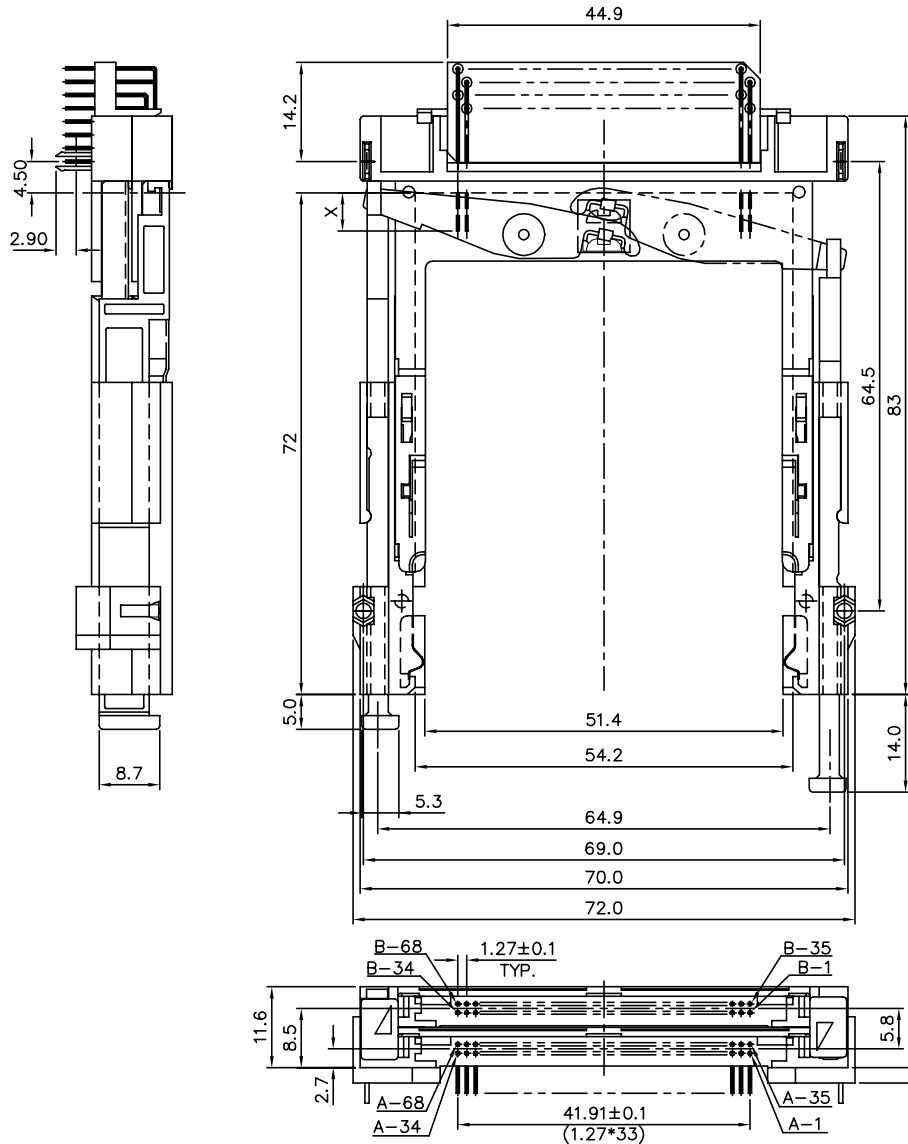
DIM "X"	4.25±0.1	3.5±0.1	5.0±0.1
PIN NUMBER	OTHERS	36,67	1,17,34,35,51,68
7. NUT M2*0.4P (2X) RETENTION FORCE : 1Kg MIN.
8. IF LEAD FREE P.N.THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM THICK CIRCUIT BOARD.
9. IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
10. LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION
11. PRODUCT SPEC: 110-263



mat'l. code	surface	tolerance	projection	product family
	ISO1302 ✓	ISO406 ISO1101		PCMCIA
l trechn nodr	date	tolerances unless otherwise specified		
M		angle	MM	68POS. EJECTOR HEADER ASS'Y FOR TYPE 1/2/3
		0°±2'	scale:5:1	
dr	c L FENG	04/06/94		dwg no
eng	JOSEPH HSIA	04/06/94		sheet 6 of 12
chr	JOSEPH HSIA	04/06/94		size
app	D K WANG	04/06/94		A4
sheet index	revision sheet			type Product Customer Drawing



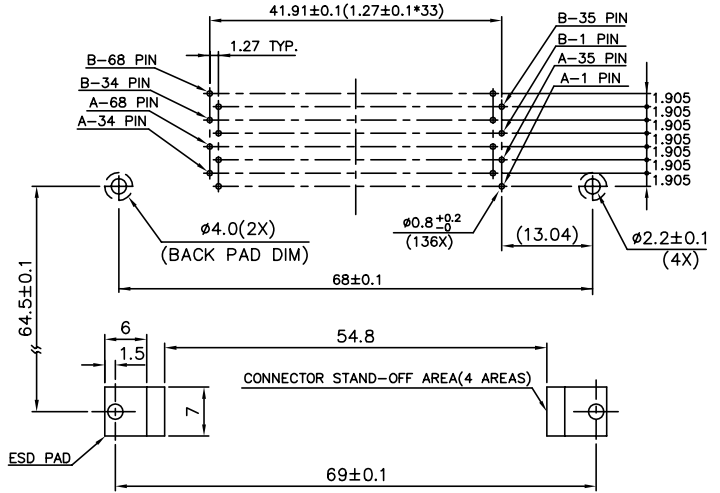
PRODUCT NO.
94721-105CA/105CALF



- NOTES:
- EJECT FORCE 3.5 Kg MAX.
 - ASSY PROCESS
 - TO MOUNT PART (A) ON PWB WITH HOLD DOWN(S1,S2)AND SOLDER THEN FIX PART (B) WITH TWO SCREWS.
 - EJECT TRAVEL: 9.0mm
 - MATERIAL
 - PART (A) (HEADER ASS'Y)
PLASTIC : HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PIN : PHOSPHOR BRONZE
 - PART (B) (EJECT MECHANISM ASS'Y)
PLASTIC : HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PLATE : STAINLESS
EMI CONTACT: PHOSPHOR BRONZE
 - FINISH (PIN)
UNDER PLATING : 0.5µm MIN. Ni
CONTACT AREA : 0.076 µm MIN. GOLD
SOLDER TAIL : 2.5µm MIN. Sn-Pb
SOLDER TAIL : 2.5µm MIN. PURE Sn (FOR *****LF)

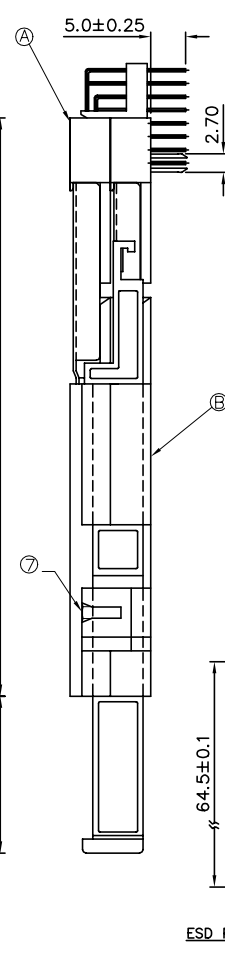
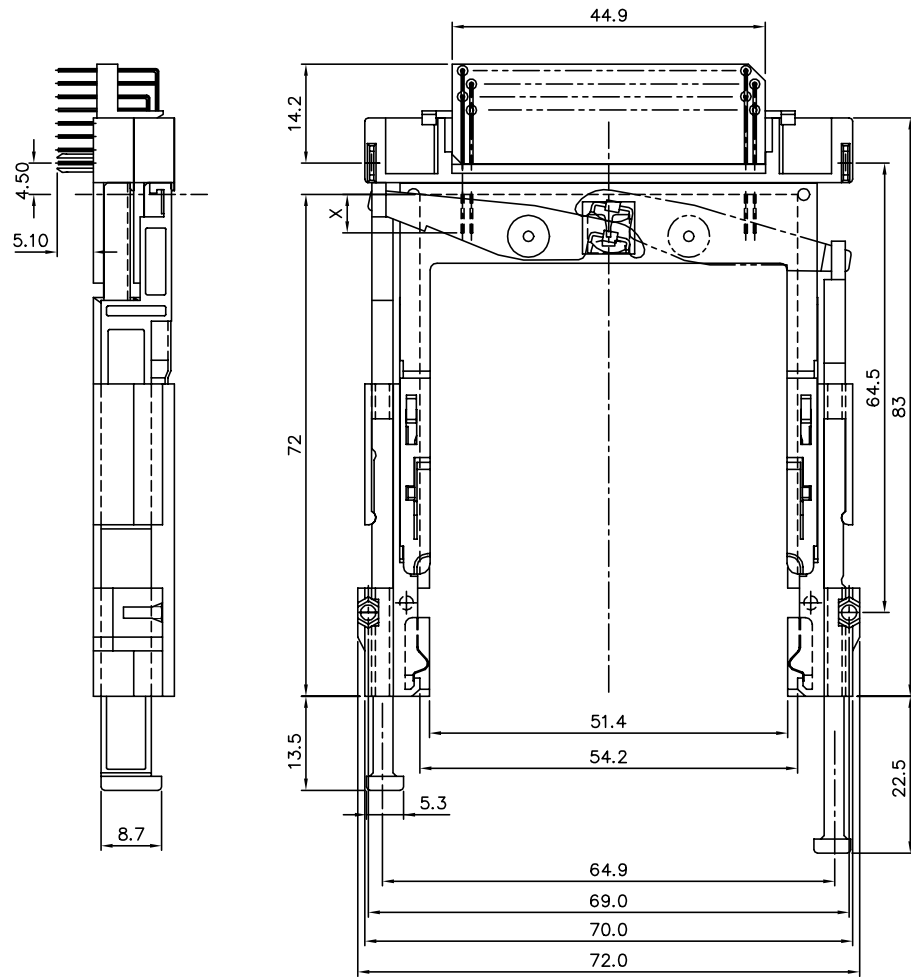
DIM "X"	4.25±0.1	3.5±0.1	5.0±0.1
PIN NUMBER	OTHERS	36,67	1,17,34,35,51,68

- NUT M2*0.4P (2X) RETENTION FORCE : 1Kg MIN.
- IF LEAD FREE P/N.THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
- IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
- LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION
- PRODUCT SPEC: 110-263



mat'l. code	surface	tolerance	projection	product family
ISD1302	ISD406 ISD1101			PCMCIA
l trechn nodr date	tolerances unless otherwise specified			
M	angle	0.X±0.3	MM	68POS. EJECTOR HEADER ASS'Y FOR TYPE 1/2/3
	0°±2'	0.XX±0.13	scale: 1.5:1	
		0.XXX±0.05		
dr	C L FENG	04/06/94		dwg no
eng	JOSEPH HSIA	04/06/94		sheet 7 of 12
chr	JOSEPH HSIA	04/06/94		size
app	D K WANG	04/06/94		A4
sheet index	revision sheet			type Product Customer Drawing

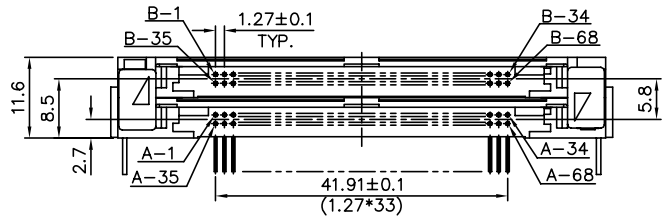
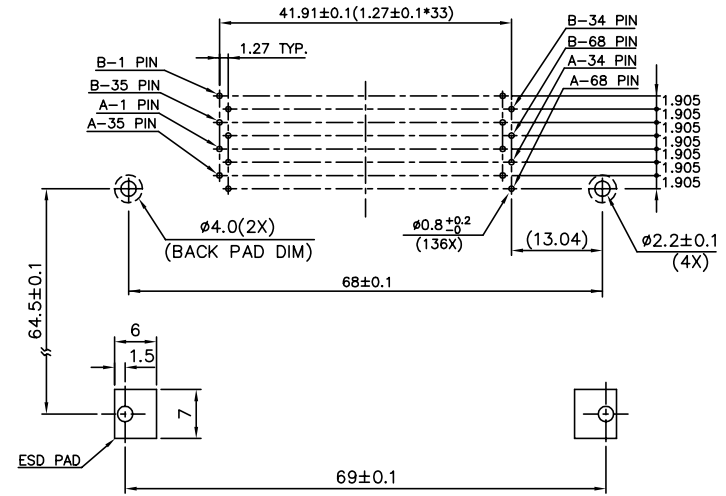
PRODUCT NO.
94721-003DA/003DALF



NOTES:

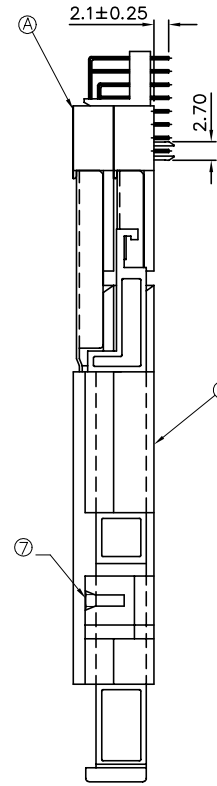
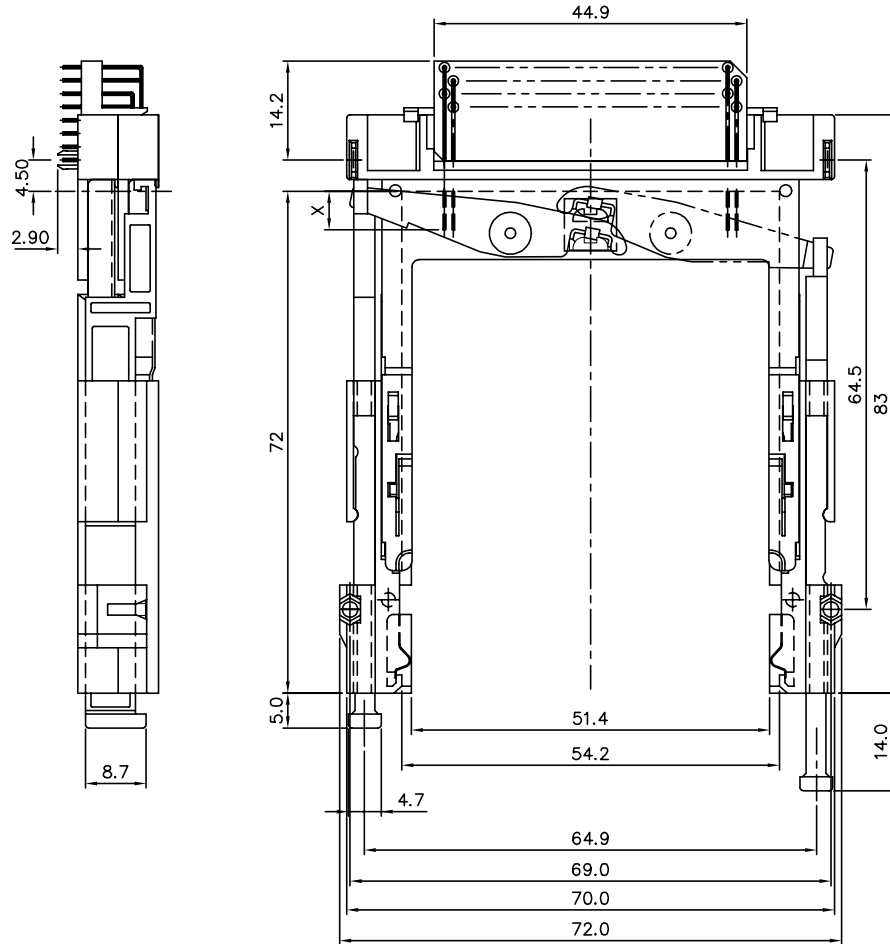
1. EJECT FORCE 3.5 Kg MAX.
2. ASSY PROCESS
 - 2.1 TO MOUNT PART (A) ON PWB WITH HOLD DOWN(S1,S2)AND SOLDER THEN FIX PART (B) WITH TWO SCREWS.
3. EJECT TRAVEL: 9.0mm
4. MATERIAL
 - 4.1 PART (A) (HEADER ASS'Y)
PLASTIC : HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PIN : COPPER ALLOY
 - 4.2 PART (B) (EJECT MECHANISM ASS'Y)
PLASTIC : HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PLATE : STAINLESS
EMI CONTACT: PHOSPHOR BRONZE
5. FINISH (PIN)
 - UNDER PLATING : 0.5µm MIN. NI
 - CONTACT AREA : 0.076 µm MIN. GOLD
 - SOLDER TAIL : 2.5µm MIN. Sn-Pb
 - SOLDER TAIL : 2.5µm MIN. PURE Sn (FOR -*****LF)
6.

DIM "X"	4.25±0.1	3.5±0.1	5.0±0.1
PIN NUMBER	OTHERS	36,67	1,17,34,35,51,68
7. NUT M2*0.4P (2X) RETENTION FORCE : 1Kg MIN.
8. IF LEAD FREE P/N.THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
9. IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
10. LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION
11. PRODUCT SPEC: 110-263



mat'l. code	surface ISO1302	tolerance ISO406 ISO1101	projection	product family PCMCIA
l trechn nodr date	tolerances unless otherwise specified		MM	68POS. EJECTOR HEADER ASS'Y FOR TYPE 1/2/3
M	angle 0°±2'	0.X±0.3 0.XX±0.13 0.XXX±0.05	scale: 5:1	sheet 8 of 12 size A4
dr	c L FENG	04/06/94		dwg no 94721
eng	JOSEPH HSIA	04/06/94		type Product Customer Drawing
chr	JOSEPH HSIA	04/06/94		
app	D K WANG	04/06/94		
sheet index	revision sheet			

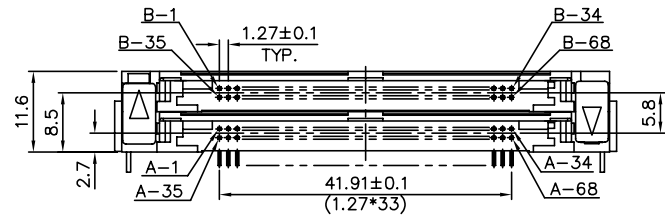
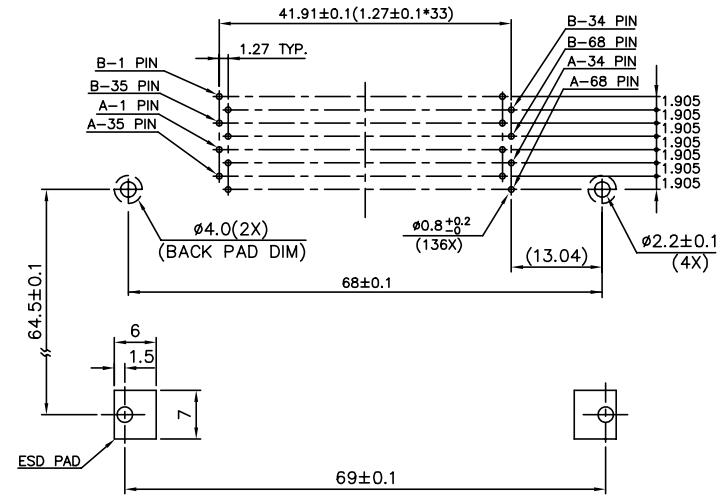
PRODUCT NO.
94721-005CA/005CALF



- NOTES:
- EJECT FORCE 3.5 Kg MAX.
 - ASS'Y PROCESS
 - 2.1 TO MOUNT PART (A) ON PWB WITH HOLD DOWN(S1,S2)AND SOLDER THEN FIX PART (B) WITH TWO SCREWS.
 - EJECT TRAVEL: 9.0mm
 - MATERIAL
 - PART (A) (HEADER ASS'Y)
PLASTIC : HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PIN : COPPER ALLOY
 - PART (B) (EJECT MECHANISM ASS'Y)
PLASTIC : HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PLATE : STAINLESS
EMI CONTACT: PHOSPHOR BRONZE
 - FINISH (PIN)
UNDER PLATING : 0.5µm MIN. NI
CONTACT AREA : 0.076 µm MIN. GOLD
SOLDER TAIL : 2.5µm MIN. Sn-Pb
 : 2.5µm MIN. PURE Sn (FOR -*****LF)

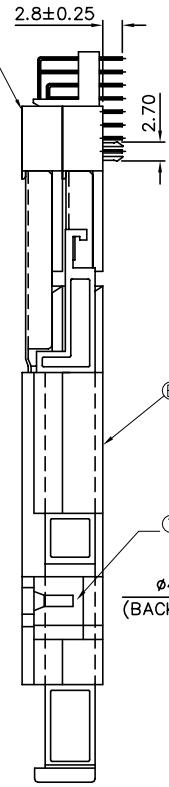
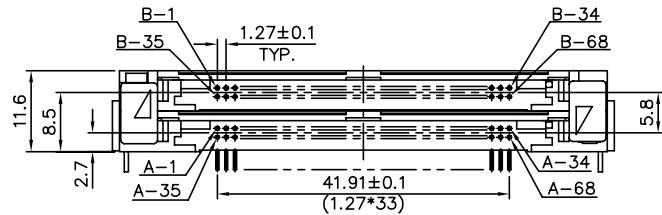
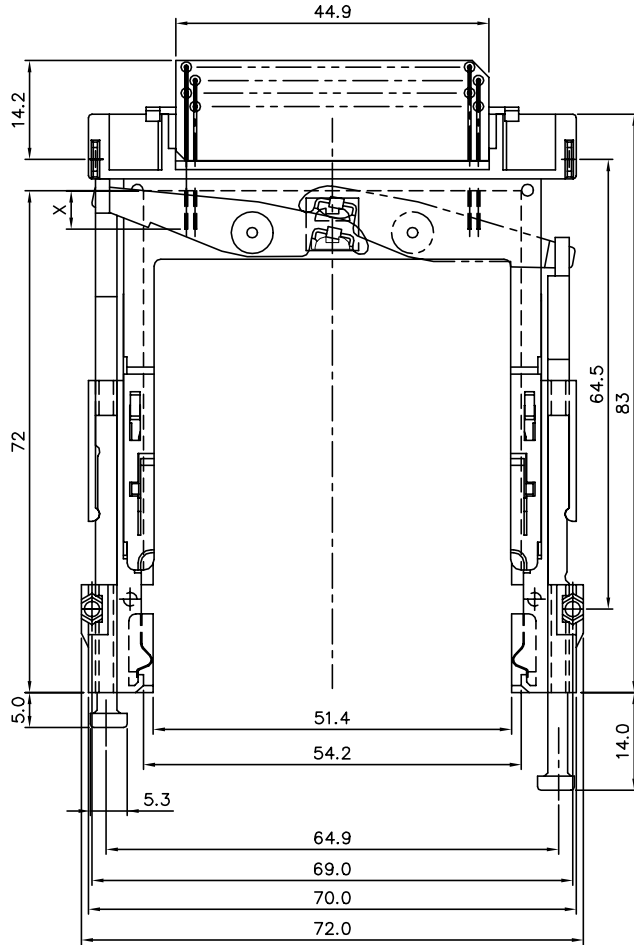
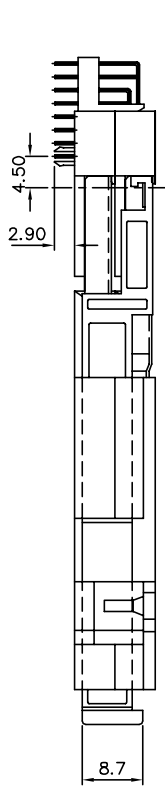
DIM "X"	4.25±0.1	3.5±0.1	5.0±0.1
PIN NUMBER	OTHERS	36,67	1,17,34,35,51,68

- NUT M2*0.4P (2X) RETENTION FORCE : 1Kg MIN.
- IF LEAD FREE P/N.THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
- IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
- LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION
- PRODUCT SPEC: 110-263



mat'l. code	surface ISO1302	tolerance ISO406 ISO1101	projection	product family PCMCIA
l trechn nodr	date	tolerances unless other wise specified	MM	68POS. EJECTOR HEADER ASS'Y FOR TYPE 1/2/3
M		angle 0°±2'	scale: 5:1	dwg no 94721
	dr c L FENG	04/06/94		sheet 9 of 12 size A4
	engr JOSEPH HSIA	04/06/94		
	chr JOSEPH HSIA	04/06/94		
	appd D K WANG	04/06/94		
sheet index	revision sheet			type Product Customer Drawing

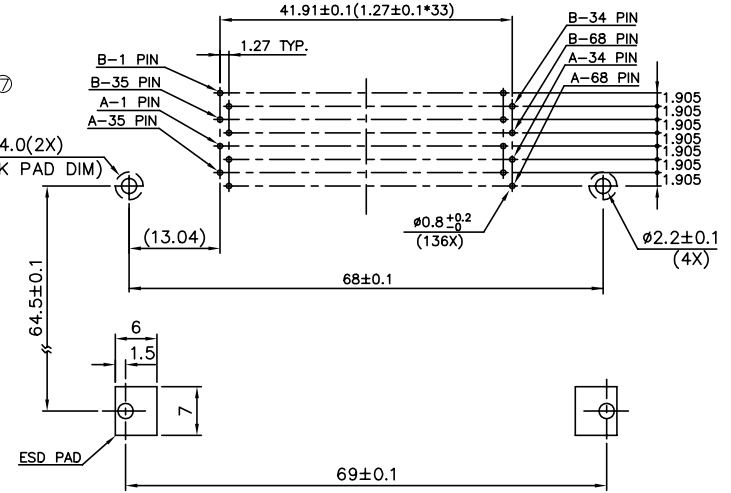
PRODUCT NO.
94721-006CA/006CALF



NOTES:
 1. EJECT FORCE 3.5 Kg MAX.
 2. ASS'Y PROCESS
 2.1 TO MOUNT PART Ⓐ ON PWB WITH HOLD DOWN(S1,S2)AND SOLDER THEN FIX PART Ⓒ WITH TWO SCREWS.
 3. EJECT TRAVEL: 9.0mm
 ④ MATERIAL
 4.1 PART Ⓐ (HEADER ASS'Y)
 PLASTIC :HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
 PIN :COPPER ALLOY
 4.2 PART Ⓑ (EJECT MECHANISM ASS'Y)
 PLASTIC :HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
 PLATE :STAINLESS
 EMI CONTACT:PHOSPHOR BRONZE
 5. FINISH (PIN)
 UNDER PLATING :0.5µm MIN. NI
 CONTACT AREA :0.076 µm MIN. GOLD
 SOLDER TAIL : 2.5µm MIN. Sn-Pb
 SOLDER TAIL : 2.5µm MIN. PURE Sn (FOR -****LF)
 6.

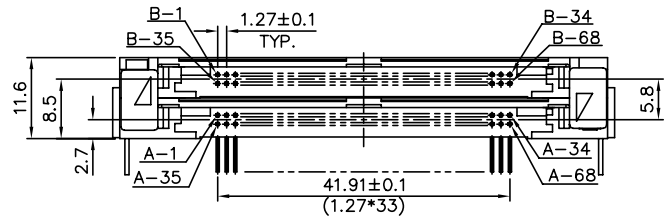
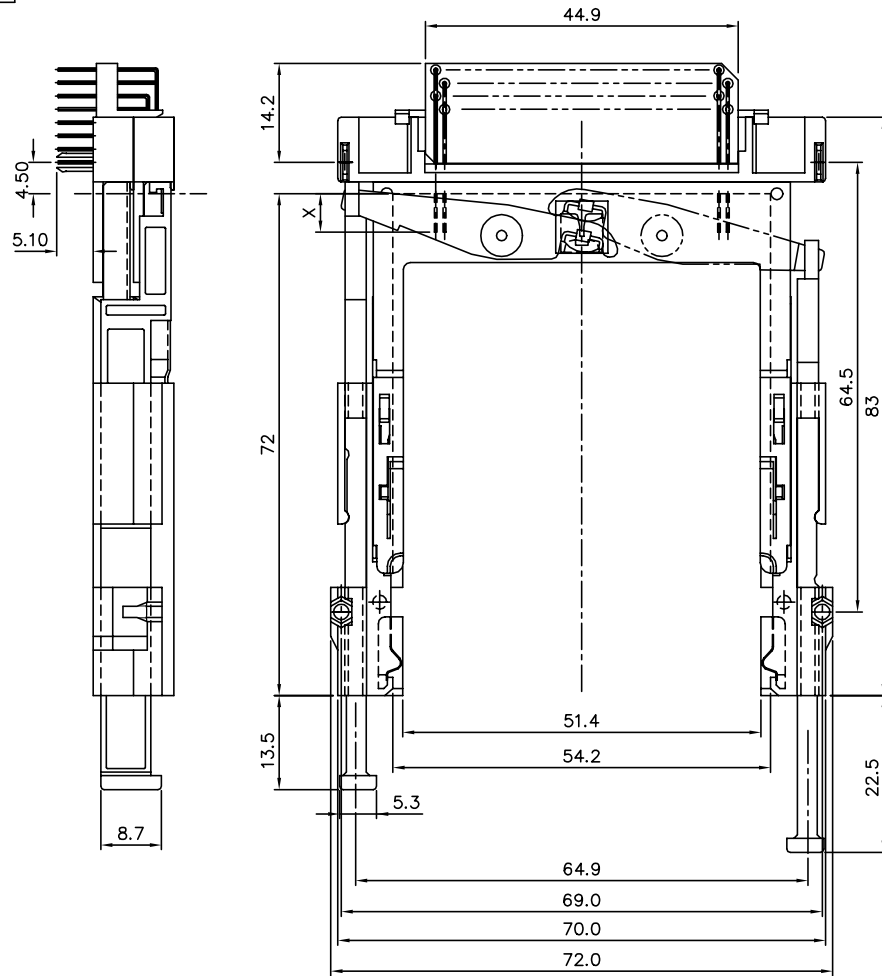
DIM "X"	4.25±0.1	3.5±0.1	5.0±0.1
PIN NUMBER	OTHERS	36,67	1,17,34,35,51,68

⑦ NUT M2*0.4P (2X) RETENTION FORCE : 1Kg MIN.
 B IF LEAD FREE P/N,THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
 9 IF LEAD FREE P/N,THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
 10 LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION
 11 PRODUCT SPEC: 110-263



mat'l. code	surface	tolerance	projection	product family
ISD1302	ISD406	ISD101	PCMCIA	
tr tecn nodr date	tolerances unless otherwise specified		MM	68POS. EJECTOR HEADER ASS'Y FOR TYPE 1/2/3
M	angle	0.X±0.3	scale:1.5:1	dwg no 94721
	0°±2'	0.XXX±0.05		sheet 10 of 12
	dr C L FENG	04/06/94		size A4
	engr JOSEPH HSIA	04/06/94		
	chr JOSEPH HSIA	04/06/94		
	app D K WANG	04/06/94		
sheet index	revision sheet			type Product Customer Drawing

PRODUCT NO.
94721-004DA/004DALF

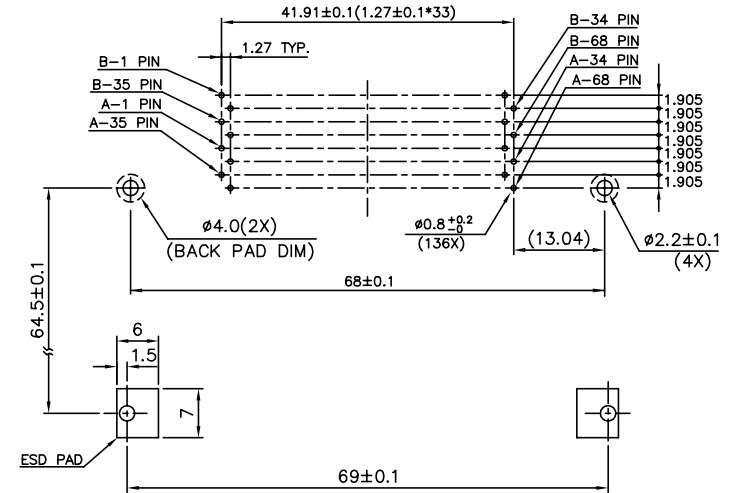


NOTES:

- EJECT FORCE 3.5 Kg MAX.
- ASS'Y PROCESS
 - TO MOUNT PART (A) ON PWB WITH HOLD DOWN(S1,S2)AND SOLDER THEN FIX PART (B) WITH TWO SCREWS.
 - EJECT TRAVEL: 9.0mm
- MATERIAL
 - PART (A) (HEADER ASS'Y)
PLASTIC :HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PIN :COPPER ALLOY
 - PART (B) (EJECT MECHANISM ASS'Y)
PLASTIC :HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PLATE :STAINLESS
EMI CONTACT:PHOSPHOR BRONZE
- FINISH (PIN)
 - UNDER PLATING :0.5µm MIN. NI
CONTACT AREA :0.076 µm MIN. GOLD
SOLDER TAIL : 2.5µm MIN. Sn-Pb
: 2.5µm MIN. PURE Sn (FOR -*****LF)

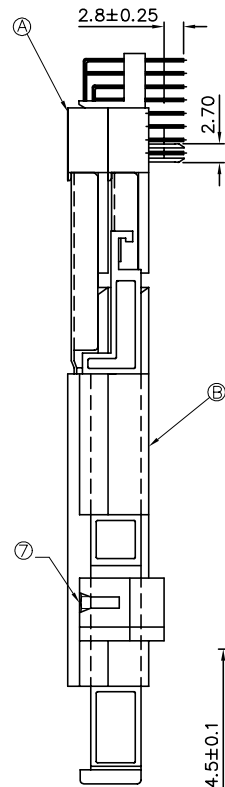
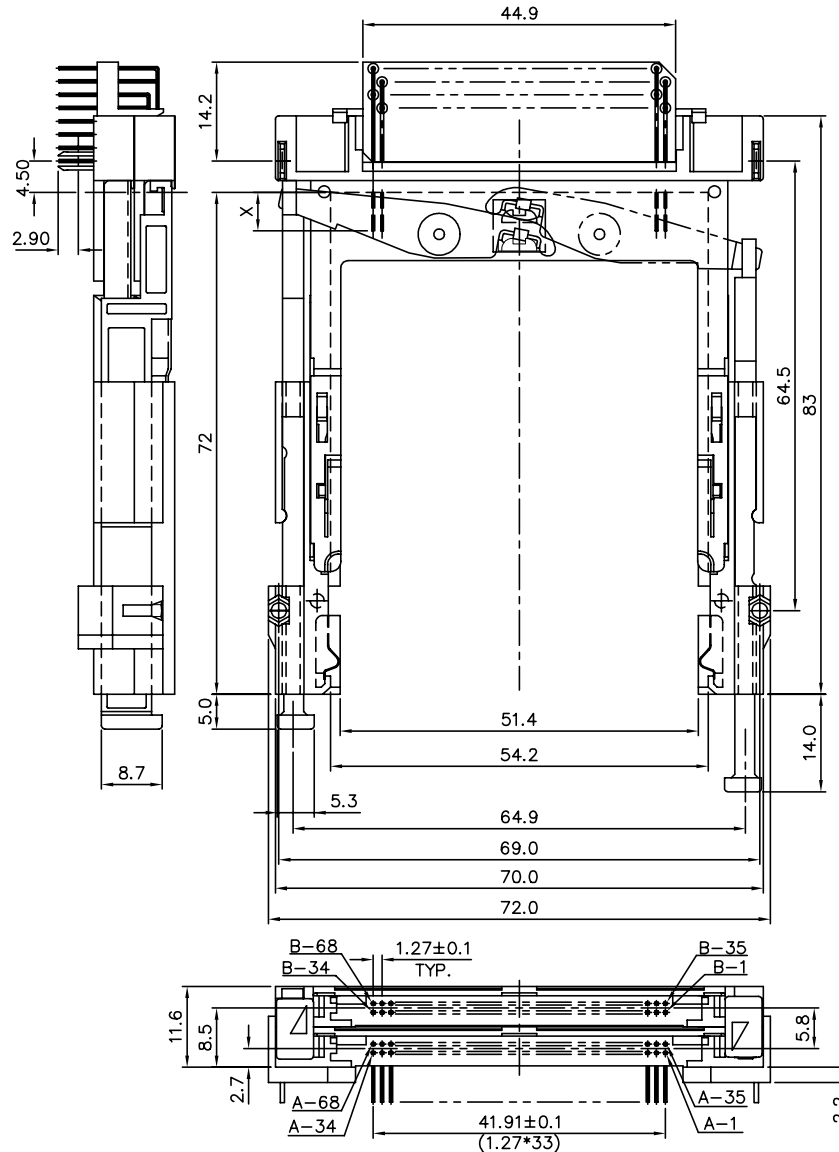
DIM "X"	4.25±0.1	3.5±0.1	5.0±0.1
PIN NUMBER	OTHERS	36,67	1,17,34,35,51,68

- NUT M2*0.4P (2X) RETENTION FORCE : 1Kg MIN.
- IF LEAD FREE P.N.THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
- IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
- LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION
- PRODUCT SPEC: 110-263



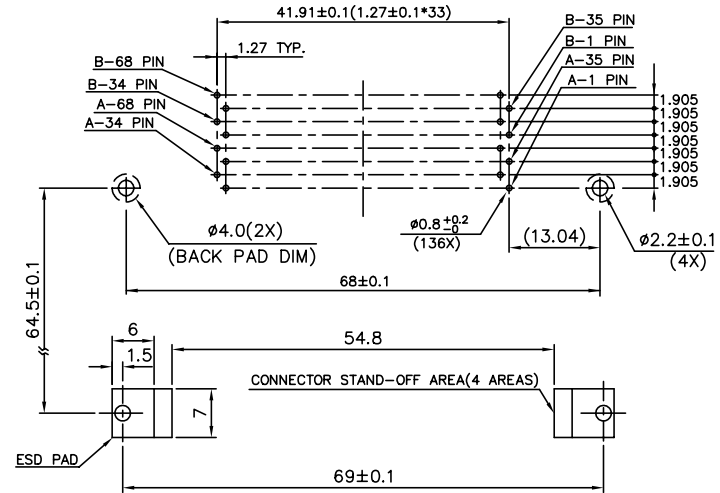
mat'l. code	surface ISO1302 ✓	tolerance ISO406 ISO1101	projection	product family PCMCIA
l'recn nodr date	tolerances unless otherwise specified	angle 0°±2'	MM	title 68POS. EJECTOR HEADER ASS'Y FOR TYPE 1/2/3
M		0.X±0.3	scale:5:1	dwg no 94721
		0.XX±0.13		sheet 11 of 12 size A4
		0.XXX±0.05		type Product Customer Drawing
dr	C L FENG	04/06/94		
eng	JOSEPH HSIA	04/06/94		
chr	JOSEPH HSIA	04/06/94		
app	D K WANG	04/06/94		
sheet index	revision sheet			

PRODUCT NO.	94721-102CA/102CALF
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NOTES:

- EJECT FORCE 3.5 Kg MAX.
- ASS'Y PROCESS
 - TO MOUNT PART A ON PWB WITH HOLD DOWN(S1,S2)AND SOLDER THEN FIX PART B WITH TWO SCREWS.
- EJECT TRAVEL: 9.0mm
- MATERIAL
 - PART A (HEADER ASS'Y)
PLASTIC :HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PIN :COPPER ALLOY
 - PART B (EJECT MECHANISM ASS'Y)
PLASTIC :HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PLATE :STAINLESS
EMI CONTACT:PHOSPHOR BRONZE
- FINISH (PIN)
UNDER PLATING :0.5µm MIN. Ni
CONTACT AREA :0.076 µm MIN. GOLD
SOLDER TAIL : 2.5µm MIN. Sn-Pb
 : 2.5µm MIN. PURE Sn (FOR -*****LF)
- | DIM "X" | 4.25±0.1 | 3.5±0.1 | 5.0±0.1 |
|------------|----------|---------|------------------|
| PIN NUMBER | OTHERS | 36,67 | 1,17,34,35,51,68 |
- NUT M2*0.4P (2X) RETENTION FORCE : 1Kg MIN.
- IF LEAD FREE P.N.THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
- IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
- LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION
- PRODUCT SPEC: 110-263



mat'l. code	surface ISO1302	tolerance ISO406 ISO1101	projection	product family PCMCIA
ltr ecn nodr date	tolerances unless otherwise specified		MM	68POS. EJECTOR HEADER ASS'Y FOR TYPE 1/2/3
M	angle	0.X±0.3	scale:5:1	dwg no 94721
	0°±2'	0.XX±0.13		sheet 12 of 12 size A4
		0.XXX±0.05		type Product Customer Drawing
dr c L FENG 04/06/94	engr JOSEPH HSIA 04/06/94	chr JOSEPH HSIA 04/06/94		
appd D K WANG 04/06/94				
sheet index	revision sheet			